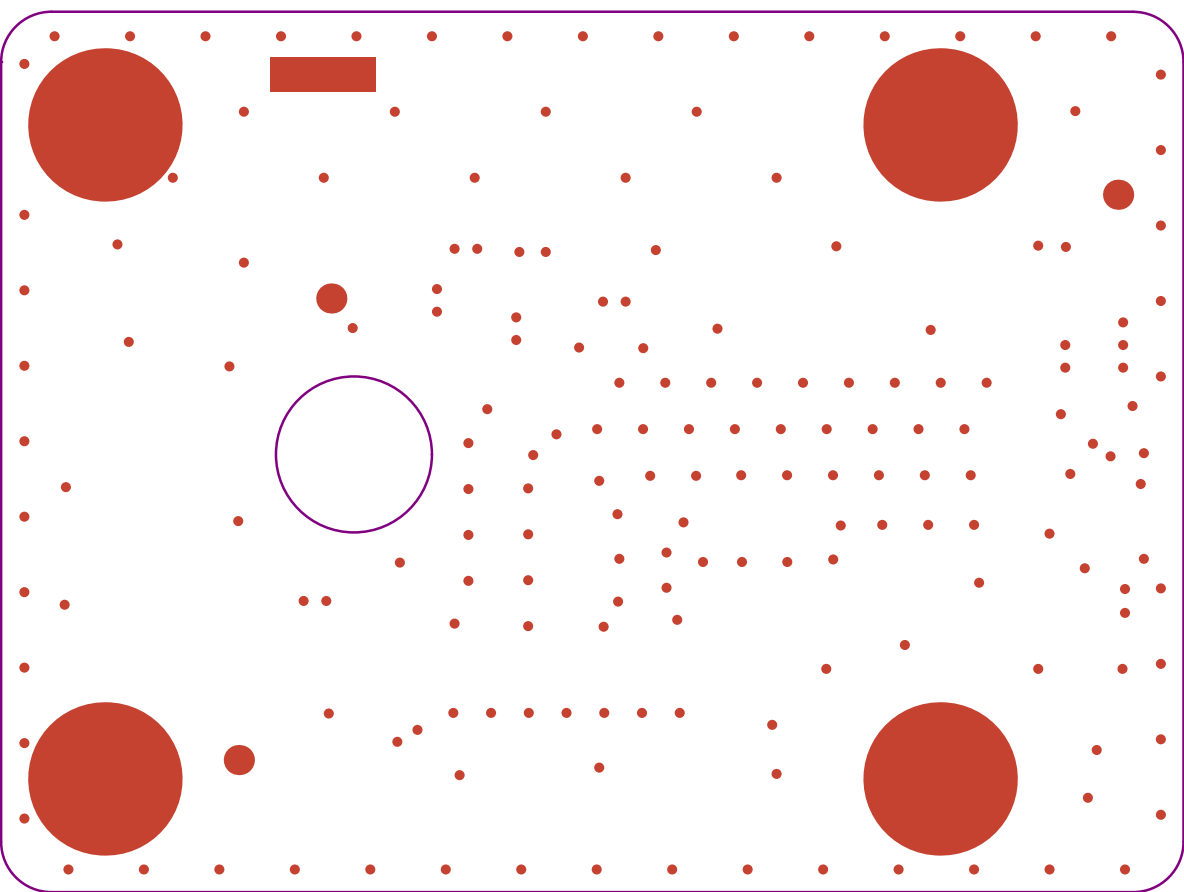


MB1897B

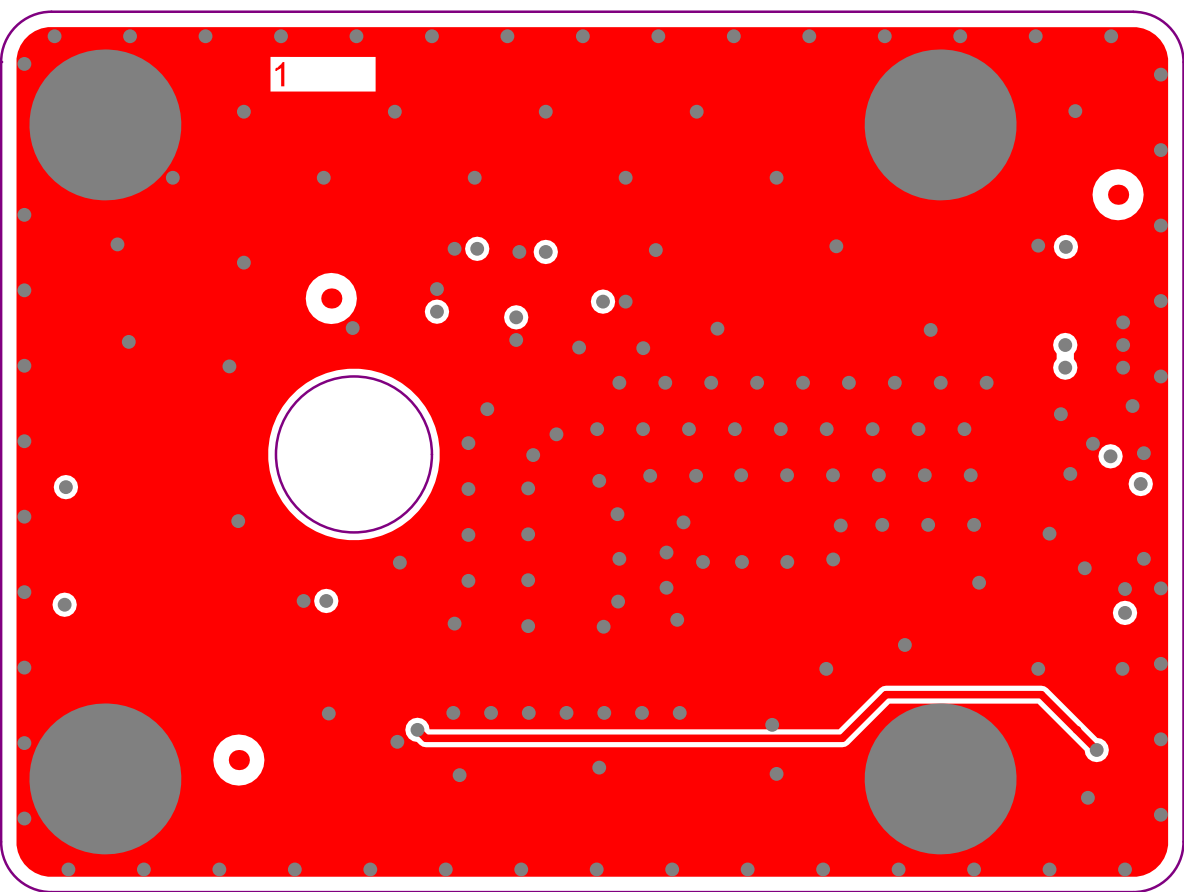
CSI Camera module





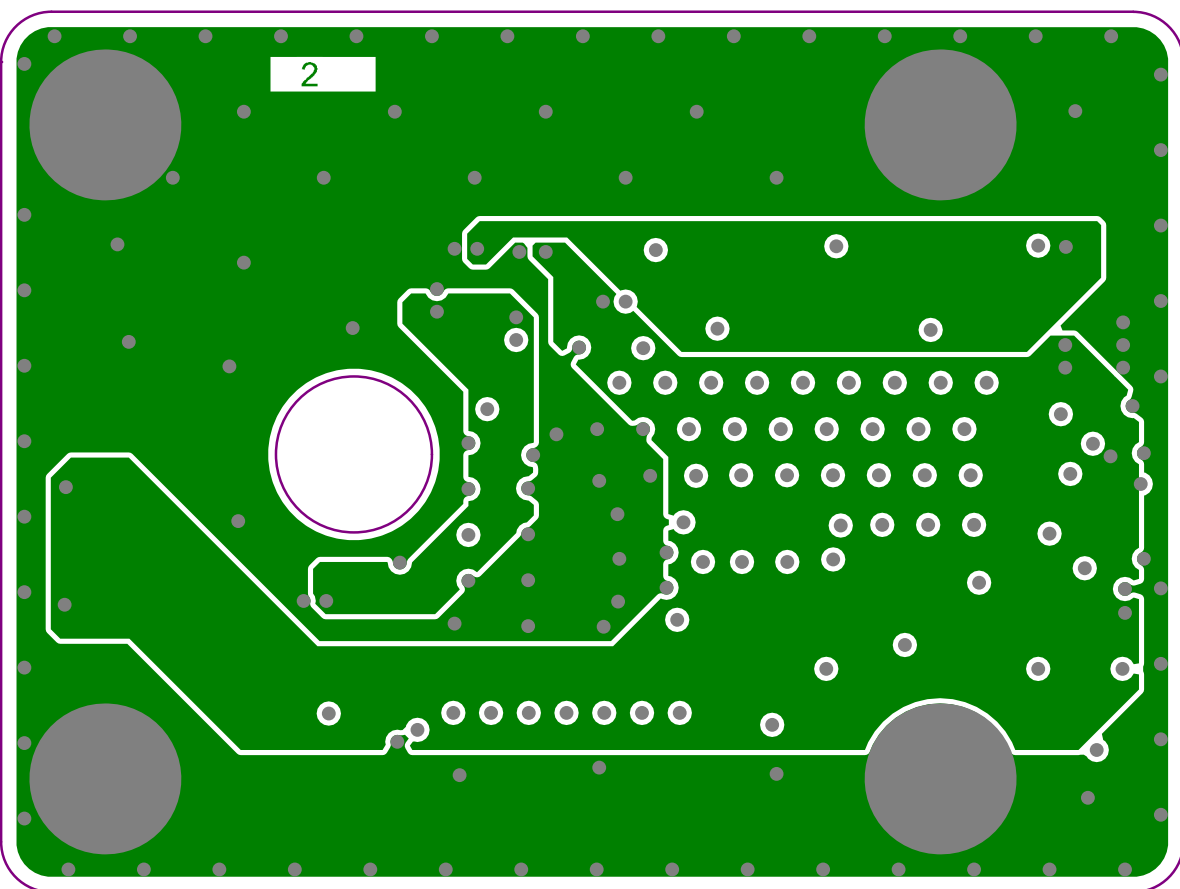
Top Solder

.GTS



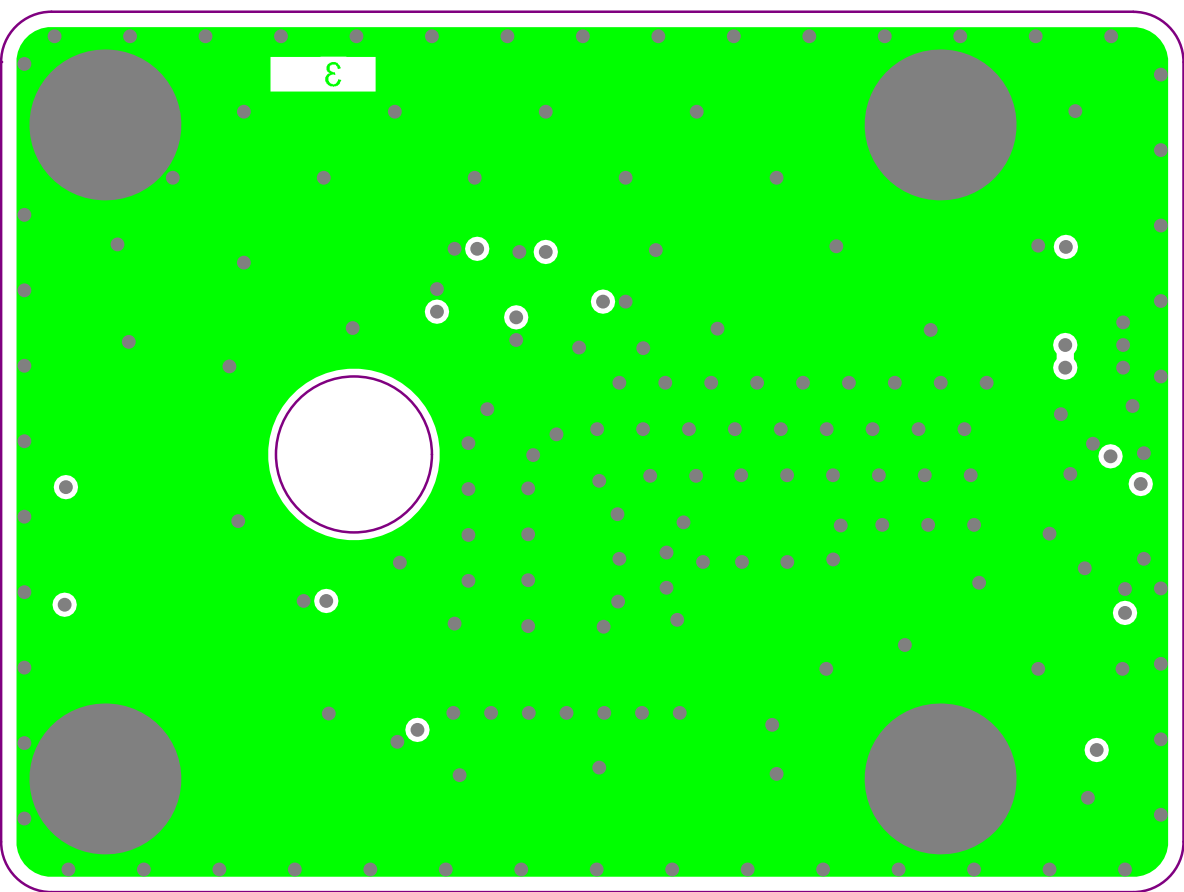
Top Layer

.GTL



Signal Layer 1

.G1



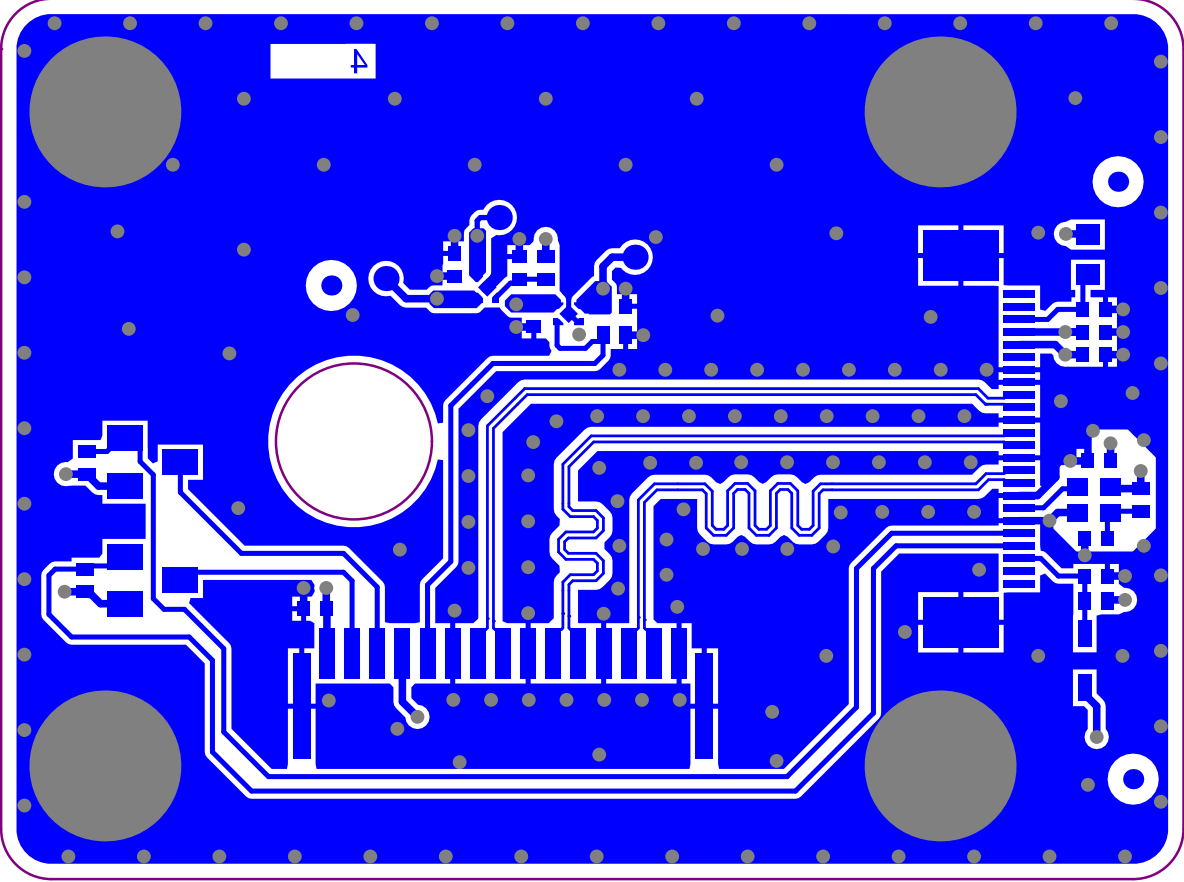
Signal Layer 2

.G2

Bottom Layer

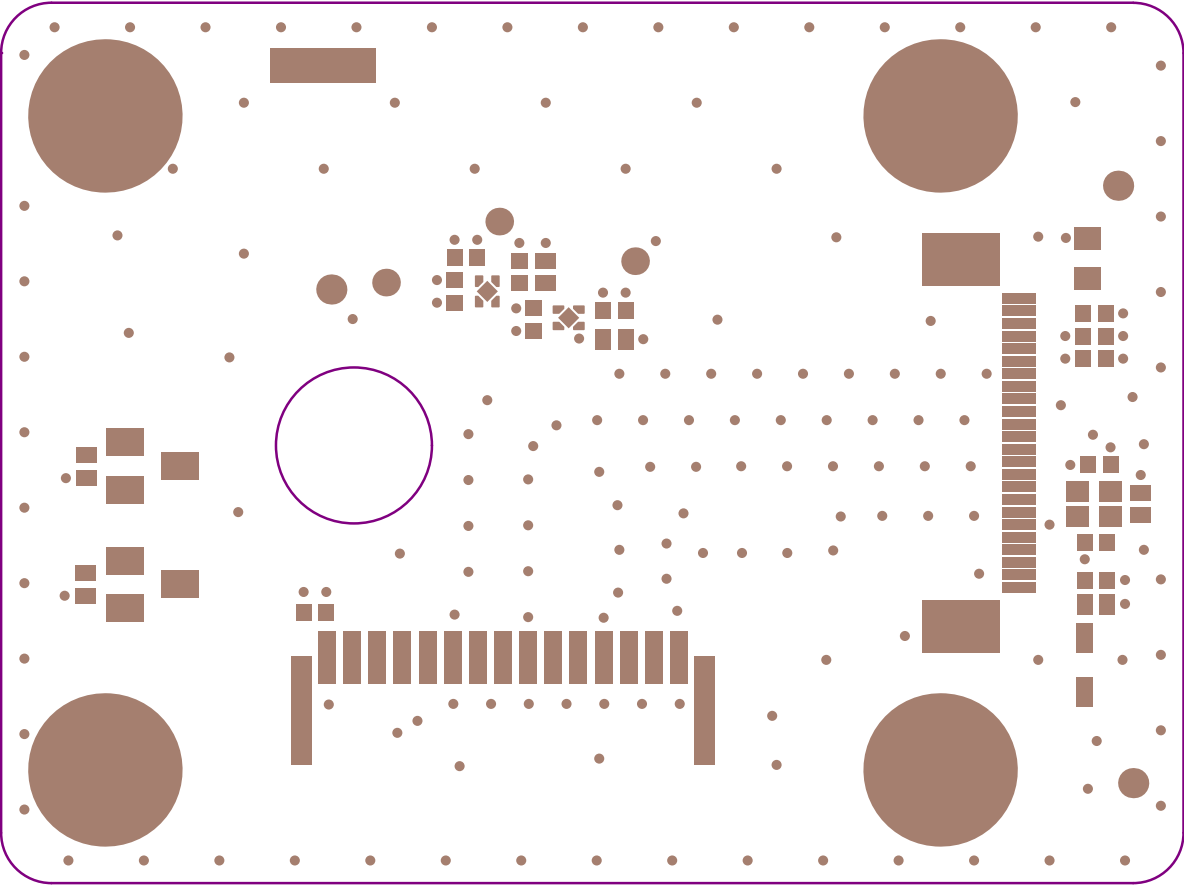


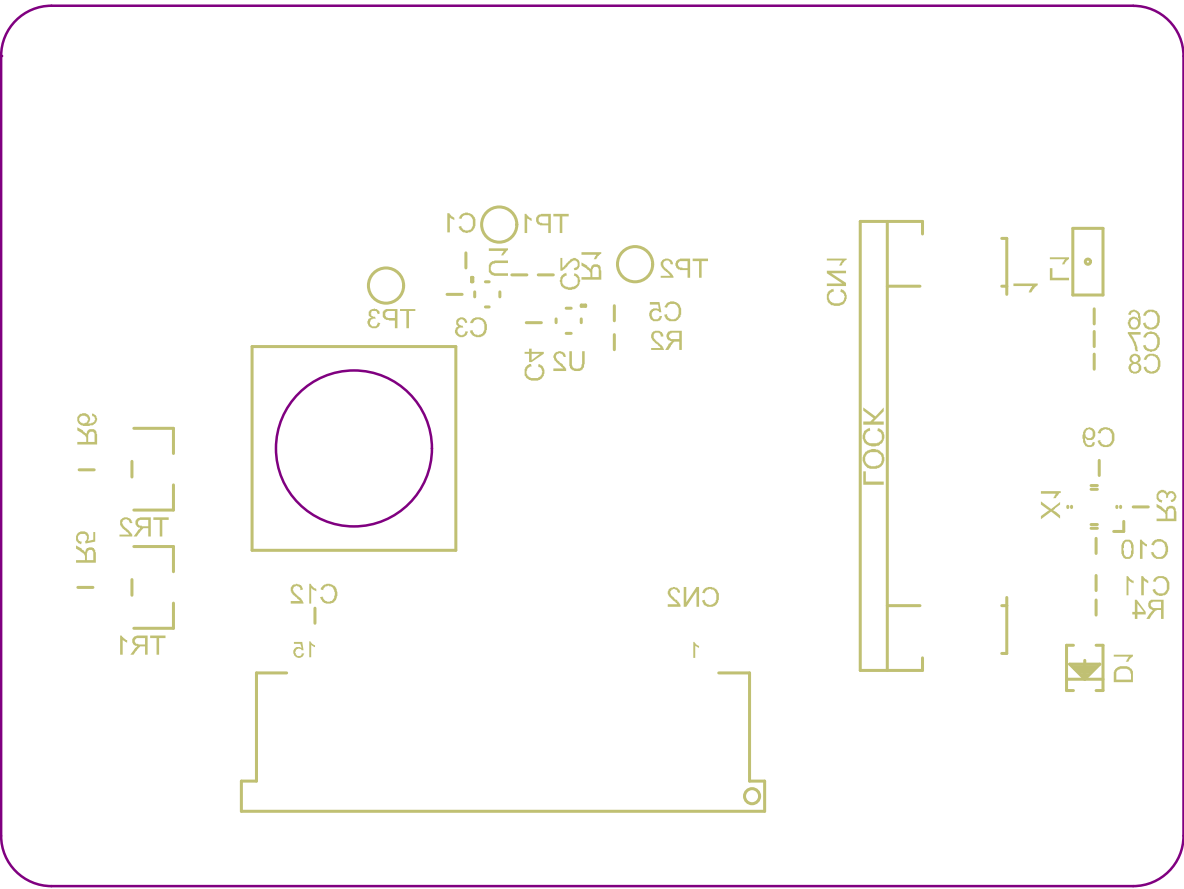
.GBL



Bottom Solder

.GB2





PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☐ BLACK

☐ RED

☒ Blue ink PANTONE 2955

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

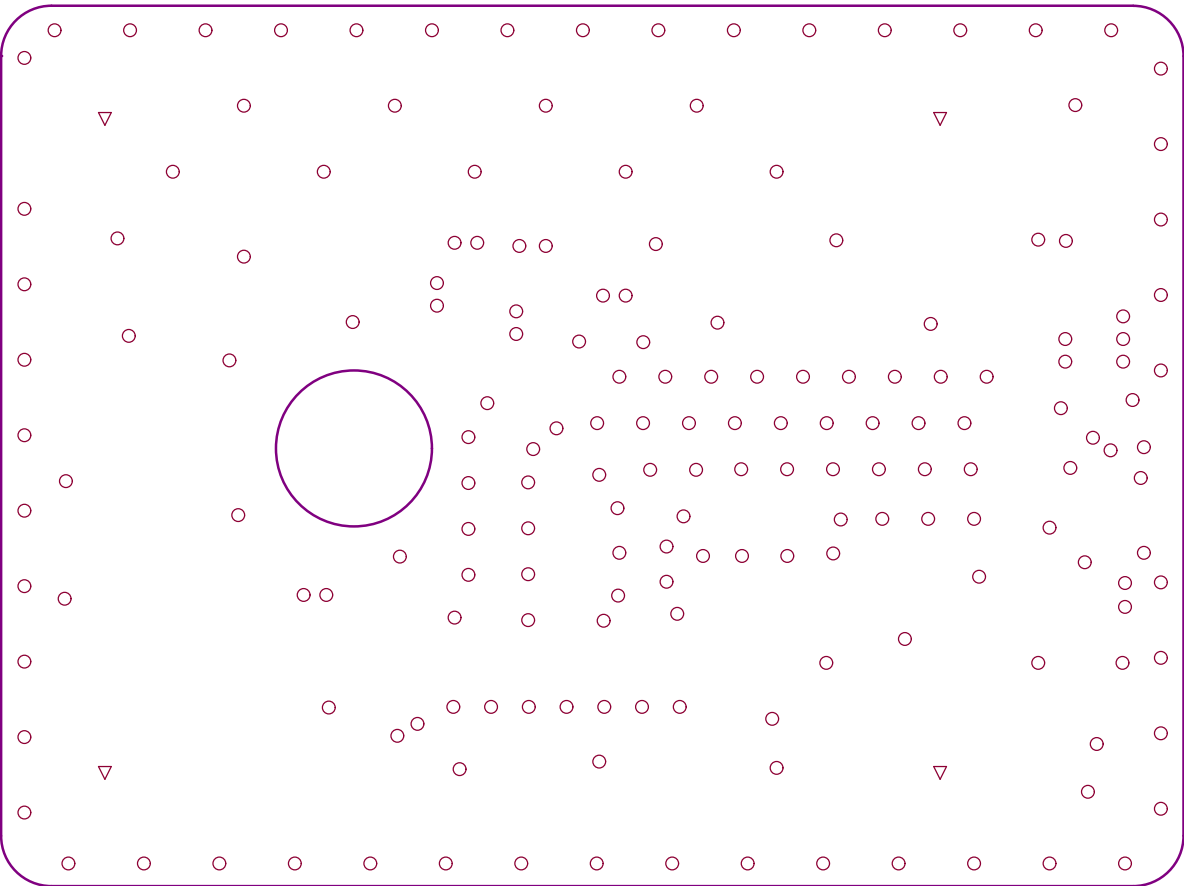
PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

MINIMUN PARAMETERS

DEFAULT
TRACKS : 0.110mm
GAPS : 0.130mm



Drill Drawing

.DRL

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,015mm	3,5	
1	Top Layer	Copper	0,037mm		
	Dielectric 2	PP-006	0,106mm	4,1	
2	Signal Layer 1	Copper	0,035mm		
	Dielectric 1	FR-4	1,200mm	4,2	
3	Signal Layer 2	Copper	0,035mm		
	Dielectric 3	PP-006	0,106mm	4,1	
4	Bottom Layer	Copper	0,037mm		
	Bottom Solder	Solder Resist	0,015mm	3,5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
▽	4	3,500mm (137,79mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
○	181	0,300mm (11,81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	185 Total						